# **ON Semiconductor**

# Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,



ON Semiconductor®

# FDB0690N1507L

# N-Channel PowerTrench® MOSFET

# 150 V, 115 A, 6.9 m $\Omega$ Features

- Max  $r_{DS(on)}$  = 6.9 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 17 A
- Fast Switching Speed
- Low Gate Charge
- $\blacksquare$  High Performance Trench Technology for Extremely Low  $R_{DS(\text{on})}$
- High Power and Current Handling Capability
- RoHS Compliant



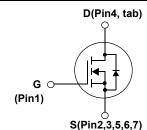
2. Source/Kelvin Sense 3. Source/Kelvin Sense

## **General Description**

This N-Channel MOSFET is produced using ON Semiconductor's advance PowerTrench® process that has been especially tailored to minimize the on-state resistance while maintaining superior ruggedness and switching performance for industrial applications.

### **Applications**

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





D2-PAK (TO263)

1. Gate

4. Drain 5. Source 6. Source 7. Source

# **MOSFET Maximum Ratings** $T_C = 25$ °C unless otherwise noted.

Symbol	Parame	eter		Ratings	Units
$V_{DS}$	Drain to Source Voltage			150	V
$V_{GS}$	Gate to Source Voltage			±20	V
I <sub>D</sub>	Drain Current -Continuous	T <sub>C</sub> = 25°C	(Note 5)	115	
	-Continuous	T <sub>C</sub> = 100°C	(Note 5)	81	Α
	-Pulsed		(Note 4)	636	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	633	mJ
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> = 25°C		250	w
	Power Dissipation	T <sub>A</sub> = 25°C	(Note 1a)	3.8	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Tempera	ature Range		-55 to +175	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	0.6	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	40	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB0690N1507L	FDB0690N1507L	D2-PAK-7L	330 mm	24 mm	800 units

# **Electrical Characteristics** T<sub>J</sub> = 25 °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	cteristics					
$BV_{DSS}$	Drain to Source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0 V	150			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		106		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V			1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### On Characteristics (Note 2)

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	3.3	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		-13		mV/°C
r	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 17 \text{ A}$		5.4	6.9	mΩ
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS}$ = 10 V, $I_{D}$ = 17 A, $T_{J}$ = 150°C		12.9	16.5	1115.2
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 17 A		60		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V, f = 1 MHz	6265	8775	pF
C <sub>oss</sub>	Output Capacitance		502	705	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		25	40	pF
$R_g$	Gate Resistance		2.5		Ω

## **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		35	56	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = 75 V, I <sub>D</sub> = 17 A,	30	48	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = 10 V, $R_{GEN}$ = 6 $\Omega$	53	85	ns
t <sub>f</sub>	Fall Time		14	25	ns
Qg	Total Gate Charge	75.77	82	115	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>DD</sub> = 75 V, I <sub>D</sub> = 17 A, V <sub>GS</sub> = 10 V	29		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	vgs 10 v	15		nC

#### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	115	Α	
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	636	Α	
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 17 \text{ A}$ (	Note 2)		0.8	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 17 A, di/dt = 100 A/μs			106	170	ns
Q <sub>rr</sub>	Reverse Recovery Charge				226	362	nC

#### Notes:

- 2. Pulse Test: Pulse Width < 300  $\mu s,$  Duty cycle < 2.0 %.
- 3. EAs of 633 mJ is based on starting  $T_J$  = 25 °C, L = 0.3 mH, IAS = 65 A,  $V_{DD}$  = 135 V,  $V_{GS}$  = 10 V. 100% test at L = 0.1 mH, IAS = 94 A.
- 4. Pulsed Id please refer to Figure "Forward Bias Safe Operating Area" for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

 $R_{0,IG}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{0,IG}$  is guaranteed by design while  $R_{0,IG}$  is determined by the user's board design.

a) 40 °C/W when mounted on a 1 in  $^2$  pad of 2 oz copper. b) 62.5 °C/W when mounted on a minimum pad of 2 oz copper.

## Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted.

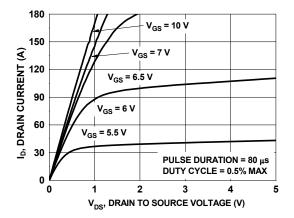


Figure 1. On Region Characteristics

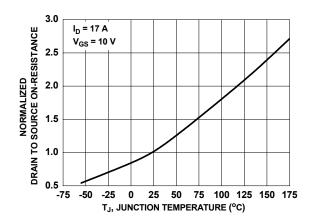


Figure 3. Normalized On Resistance vs. Junction Temperature

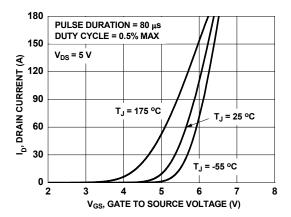


Figure 5. Transfer Characteristics

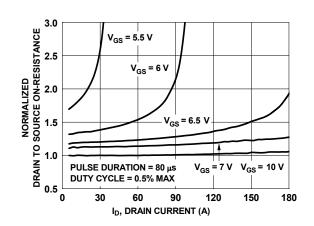


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

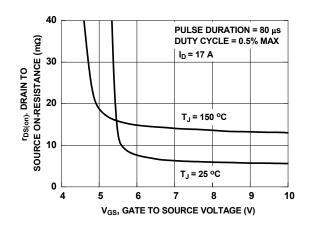


Figure 4. On-Resistance vs. Gate to Source Voltage

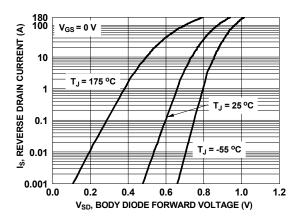


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted.

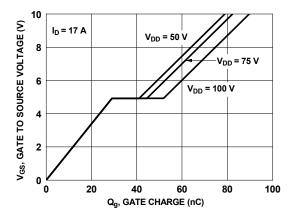


Figure 7. Gate Charge Characteristics

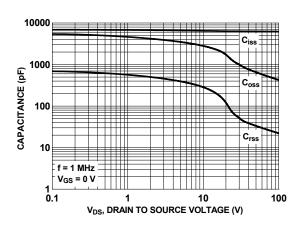


Figure 8. Capacitance vs. Drain to Source Voltage

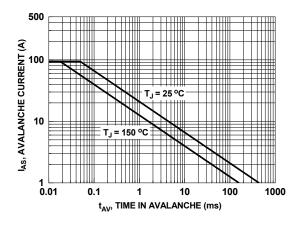


Figure 9. Unclamped Inductive Switching Capability

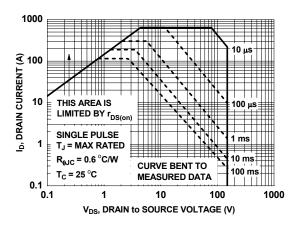


Figure 10. Forward Bias Safe Operating Area

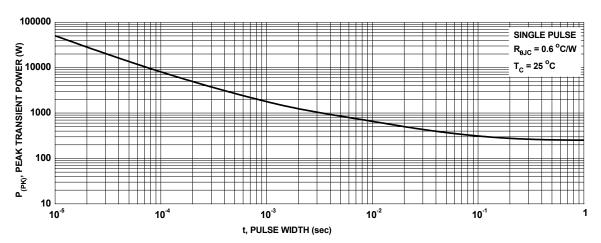


Figure 11. Single Pulse Maximum Power Dissipation



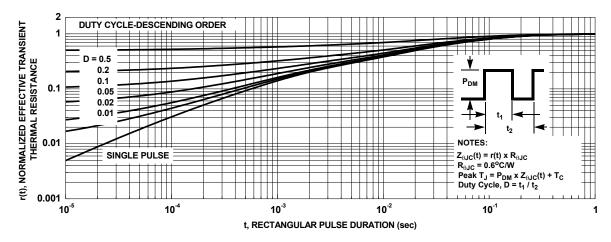


Figure 12. Junction-to-Case Transient Thermal Response Curve

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by ON Semiconductor manufacturer:

Other Similar products are found below:

614233C 648584F IRFD120 JANTX2N5237 FCA20N60\_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D TPCC8103,L1Q(CM MIC4420CM-TR VN1206L SBVS138LT1G 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C BUK954R8-60E NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE222 NTE2384 NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956 NTE2956 NTE2911 DMN2080UCB4-7 TK10A80W,S4X(S SSM6P69NU,LF DMP22D4UFO-7B